HD Communications Corp.

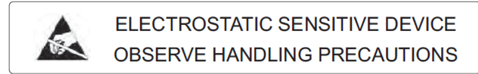
P/N : HD34389
MEMS BAND PASS FILTER

Features:

- Pass Band : 2.0 ~ 6.0 GHz
- Insertion Loss : 4.5dB
- Size : 7.5x20.0x0.5mm

Absolute Maximum Ratings

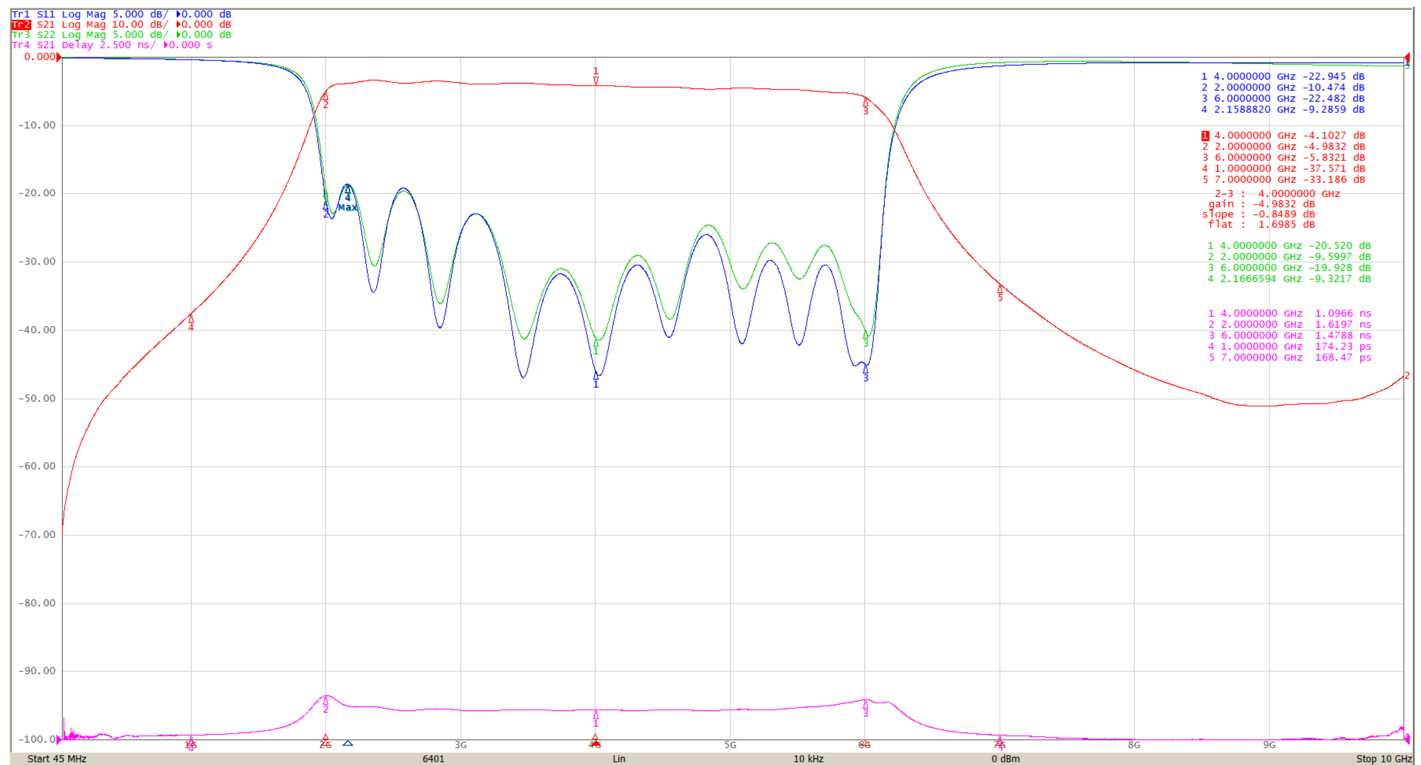
- Max. Input Power : +35dBm
- Storage Temperature : -55 ~ +85Deg.C
- Operating Temperature : -55 ~ +125Deg.C



Electrical Specifications (T_A=+25Deg.C, 50Ω system)

Parameter		Min.Value	Typical Value	Max.Value	Unit
Frequency Range			2.0~6.0		GHz
Insertion Loss		-	4.10	4.5	dB
Ripple		-	1.69	2.0	dB
Attenuation	DC~@1GHz	30	37.57	-	dB
	@7.0GHz	30	33.18	-	dB
Return Loss		7.5	9.0	-	dB
Group Delay		-	1.61	2.5	ns

Test Curve



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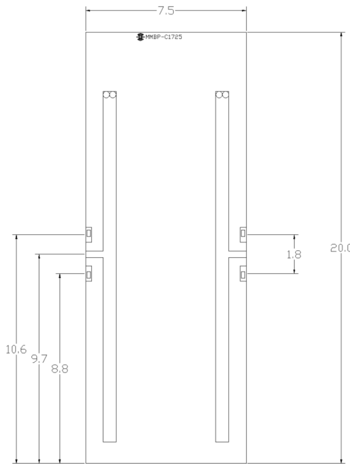
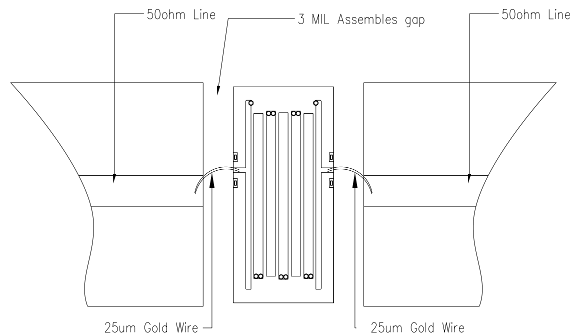


Remarks:Unit : mm, Tolerance : ±0.25mm
1. Chip bottom is gold plated and grounded.
2. Bonding pressure points are gold plated.
3. Don`t bond on the through holes.

Applications

1. Assembly and Bonding Diagram. (Reference)



Assembly Diagram

2. The chip is back-metalized and can be die mounted with AuSn eutectic performs or with electrically conductive epoxy (for example ME8456).

3. The die should be assembled on carriers like Kovar or Mu-Cu which have same Coefficient of thermal expansion. (2.9ppm/℃) with Silicon, thickness 0.2mm max.

4. Handle the chips in a clean environment. DO NOT attempt to clean the chip using liquid cleaning systems.

5. Handle the chip along the edges with a vacuum collet or with a sharp pair of bent tweezers.

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